

Appl. No. 09/852,847
Amendment and/or Response
Reply to the Office Action of June 30, 2004

Page 3 of 9

Amendments to the Claims:

A clean version of the entire set of pending claims (including amendments to the claims, if any) is submitted herewith per 37 CFR 1.121(c). This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1-17. (Cancelled)

18. (Previously Presented) A semiconductor device, comprising:

- a semiconductor element having a circuit forming surface and a parallel confronting surface;

- a wiring disposed on said circuit forming surface and on a side surface of said semiconductor element;

- a sealed bump electrode connected to said wiring, said sealed bump electrode having an exposed surface;

- an outer electrode disposed on said exposed surface of said bump electrode and contacting said wiring on said side surface of said semiconductor element; and
- wherein said parallel confronting surface is sealed.

19. (Previously Presented) A semiconductor device as recited in claim 18, further comprising a plurality of electrodes on said circuit forming surface.

20. (Previously Presented) A semiconductor device as recited in claim 18, wherein said wiring on said side surface has an end that is sealed.

21. (Previously Presented) A semiconductor device as recited in claim 18, wherein said sealed bump electrode and said sealed confronting surface are resin sealed.

Appl. No. 09/852,847
Amendment and/or Response
Reply to the Office Action of June 30, 2004

Page 4 of 9

22. (Previously Presented) A semiconductor device as recited in claim 18, wherein said sealed confronting surface is entirely sealed.

23. (Previously Presented) A semiconductor device as recited in claim 18, wherein the semiconductor device is mounted on another semiconductor device with said confronting surface as a contacting surface.

24. (Previously Presented) A semiconductor device as recited in claim 23, wherein said another semiconductor device has electrodes that are connected to said wiring of the semiconductor device.

25. (Previously Presented) A semiconductor device as recited in claim 19, wherein the semiconductor device is mounted on another semiconductor device with said confronting surface as a contacting surface, and said another semiconductor device has electrodes that are connected to said wiring and to at least one of said plurality of electrodes.

26. (Previously Presented) A semiconductor device as recited in claim 23, wherein said another semiconductor device is disposed over a plurality of other semiconductor devices.

27. (Cancelled)

28. (Previously Presented) A semiconductor device as recited in claim 18, wherein said circuit forming surface is sealed.

29. (Previously Presented) A semiconductor device as recited in claim 28,

Atty. Docket No. OKI.234

Appl. No. 09/852,847
Amendment and/or Response
Reply to the Office Action of June 30, 2004

Page 5 of 9

wherein said circuit forming surface and said parallel confronting surface are resin sealed.

Atty. Docket No. OKI.234